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Attorney Docket No.: CPAC 1029-5

**CERTIFICATE OF TRANSMISSION UNDER 37 CFR 1.8**

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to the United States Patent and Trademark Office at Fax No. (703) 872-9306  
on 21 March 2005.

  
Paula Hurley 21 March 2005

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:  
Marcos Karnezos

Application No. 10/681,583

Confirmation No.: 6814

Filed: 08 October 2003

Title: Semiconductor Multi-Package Module  
Having Inverted Second Package Stacked Over  
Die-down Flip-chip Ball Grid Array (BGA)  
Package

Group Art Unit: 2841  
Examiner: Unassigned.

**CUSTOMER NO. 22470**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**STATUS INQUIRY**

Sir:

The last correspondence received from the Patent Office for the subject application is a Filing  
Receipt mailed 09 March 2004. Please inform the undersigned when this application will be examined.

Dated: 21 March 2005

Respectfully submitted,

 By, No. 33,407  
Bill Kennedy, Reg. No. 33,407

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